



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

ATTY.'S DOCKET: 98 P7501 US 01

1746
19/E
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1-9-2

In re the application of:)
Ramachandran et al.) Group Art: 1746
)
Serial No.: 09/204,706) Examiner: A. Olsen
)
Filing Date: December 3, 1998)
)
Title: REMOVAL OF POST-RIE POLYMER)
ON Al/Cu METAL LINE)

AMENDMENT UNDER 37 C.F.R. §1.115

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JAN 09 2002

TC 1700

Honorable Commissioner of Patents and Trademarks
Washington, D.C. 20231

Sir:

In reply to the Office Action mailed December 18, 2001,
which rejected the claims in the above-identified patent
application, applicants respectfully request reconsideration,
based upon the amendments hereinafter set forth.

IN THE CLAIMS:

13. (Thrice Amended) In a metal etch tool for removing
post-RIE polymer rails formed on a Al/Cu metal line of a
semiconductor structure, the improvement comprising an
integrated metal etch tool comprising therein:

- a) strip chamber means for water only plasma to strip
[the] photo-resist [layer] of a semiconductor composite
structure [with water only plasma] subsequent to a RIE to
limit thickness of sidewall polymer;
- b) vacuum chamber means to chemically modify